The invention claimed is:

1. Electroplating apparatus comprising:

a vessel for holding an electroplating solution;

a head including a rotor having a contact ring and a head motor for rotating the rotor;

a lift/rotate actuator attached to the head;

a deplate station having a deplate channel adapted to receive a sector of the contact ring;

a deplate head pivotally attached to a deplate housing of the deplate station;

with the lift/rotate actuator movable to engage the head with the vessel during plating operations, and to position a sector of the contact ring at least partially into the deplate channel;

with the deplate station having a housing fixed in place at an upper rim of the vessel, and positioned to the outside of the vessel to avoid interfering with engagement of the head with the vessel;

a first deplate electrode and a first deplate fluid nozzle on a first side of the deplate channel; and

a second deplate electrode and a second deplate fluid nozzle on a second side of the deplate channel.

2. The apparatus of claim **1** further including a seal on the deplate station positioned to make sliding contact with the contact ring, as the contact ring rotates through the deplate channel.

3. The apparatus of claim **2** further including a vacuum exhaust opening in the deplate station adjacent to the seal.

4. The apparatus of claim **1** further comprising at least 360 individual spaced apart contacts on the contact ring.

5. The apparatus of claim **1** with the deplate channel forming an arcuate slot subtending an arc of 45 to 100 degrees.

6. The apparatus of claim **1** further including a deplate head actuator attached to the deplate head for pivoting the deplate head relative to the deplate housing.

7. Electroplating apparatus comprising:

a vessel for holding an electroplating solution;

a rotor having a contact ring;

a deplate head having a deplate channel;

a deplate head actuator attached to the deplate head for moving the deplate head to a first position and to a second position;

a lift/rotate actuator for moving the rotor to position the contact ring in the vessel to electroplate a substrate, and for moving the rotor to position a sector of the contact ring at least partially into the deplate channel;

with the deplate head having at least one deplate electrode and at least one deplate fluid nozzle for deplating contacts on the contact ring; and with the deplate head pivotal from the first position to the second position via the deplate head actuator, and wherein the first position is closer to the vessel than the second position.

8. The apparatus of claim **7** where the deplate channel is facing to one side when the deplate head is in the second position.

9. The apparatus of claim **7** with the deplate head having a first deplate electrode and a first deplate fluid nozzle on a first side of the deplate channel; and

a second deplate electrode and a second deplate fluid nozzle on a second side of the deplate channel.

10. The apparatus of claim **7** further including two or more wafer shelves on the contact ring, and at least one shelf nozzle in the deplate head for spraying a gas onto the wafer shelves as the contact ring is rotated through the deplate channel.

11. The apparatus of claim **7** with the deplate head pivotally attached to a deplate housing of a deplate station having a deplate channel adapted to receive a sector of the contact ring, with the deplate housing fixed in place at an upper rim of the vessel, and positioned to the outside of the vessel.

12. The apparatus of claim **11** further including a seal on the deplate station positioned to make sliding contact with the contact ring, as the contact ring rotates through the deplate channel.

13. The apparatus of claim **12** further including a vacuum exhaust opening in the deplate station adjacent to the seal, and at least 360 individual spaced apart contacts on the contact ring.

14. The apparatus of claim **13** with the deplate channel forming an arcuate slot subtending an arc of 45 to 100 degrees.

15. Electroplating apparatus comprising:

a vessel for holding an electroplating solution;

a rotor having a contact ring;

a deplate head having a deplate channel;

a deplate head actuator attached to the deplate head for pivoting the deplate head relative to the vessel to a first position and to a second position;

a lift/rotate actuator for moving the rotor to position the contact ring in the vessel to electroplate a substrate, and for moving the rotor to position a sector of the contact ring at least partially into the deplate channel;

with the deplate head having at least one deplate electrode and at least one deplate fluid nozzle for deplating contacts on the contact ring.

16. The apparatus of claim **15** with the first position closer to the vessel than the second position.

17. The apparatus of claim **15** with the deplate head pivotally attached to a deplate housing of a deplate station having a deplate channel adapted to receive a sector of the contact ring, with the deplate housing fixed in place at an upper rim of the vessel, and positioned to the outside of the vessel.

18. The apparatus of claim **17** further including a seal on the deplate station positioned to make sliding contact with the contact ring, as the contact ring rotates through the deplate channel.

19. The apparatus of claim **18** further including a vacuum exhaust opening in the deplate station adjacent to the seal, at least 360 individual spaced apart contacts on the contact ring.

20. The apparatus of claim **19** with the deplate channel forming an arcuate slot subtending an arc of 45 to 100 degrees.